



Material Content Data Sheet



Sales Product Name				IPB60R060C7		Issued		1. August 2018	
MA#				MA002103748					
Package				PG-TO263-3-2		Weight*		1563.05 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	10.303	0.66	0.66	6591	6591	
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58		
	non noble metal	iron	7439-89-6	0.304	0.02		195		
	non noble metal	copper	7440-50-8	304.026	19.45	19.48	194508	194761	
	non noble metal	aluminium	7429-90-5	5.414	0.35	0.35	3463	3463	
wire	non noble metal	aluminium	7429-90-5	5.414	0.35	0.35	3463	3463	
encapsulation	organic material	carbon black	1333-86-4	10.168	0.65		6505		
	plastics	epoxy resin	-	111.847	7.16		71557		
	inorganic material	silicondioxide	60676-86-0	555.844	35.54	43.35	355614	433676	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6178	6178	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147	
solder	non noble metal	tin	7440-31-5	0.136	0.01		87		
	noble metal	silver	7440-22-4	0.170	0.01		109		
	non noble metal	lead	7439-92-1	6.487	0.42	0.44	4150	4346	
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105		
	non noble metal	iron	7439-89-6	0.548	0.04		351		
	non noble metal	copper	7440-50-8	547.666	35.04	35.09	350382	350838	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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